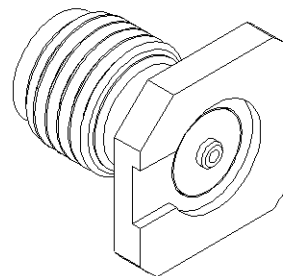
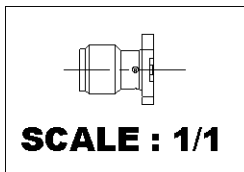
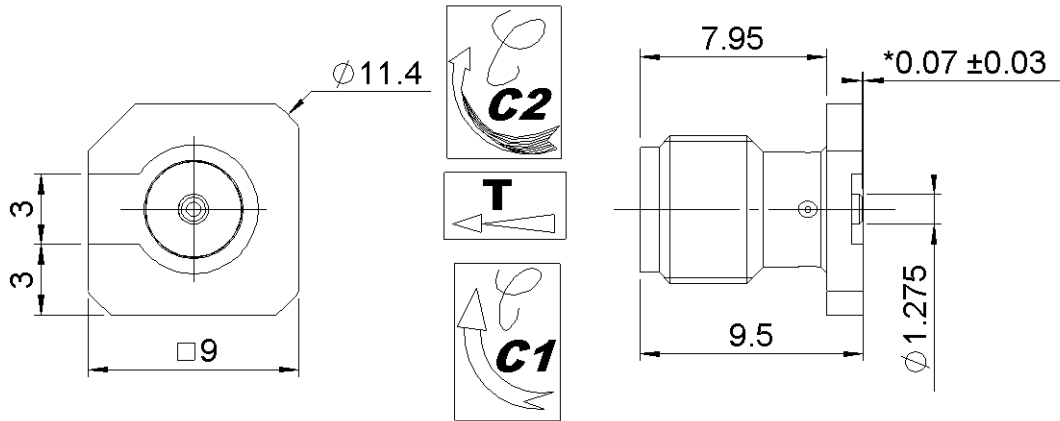
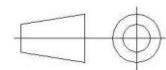


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***Set back of c. contact from body
(Retrait du c. central / au corps)**



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	NPGR
Center contact	BERYLLIUM COPPER	NPGR
Outer contact	-	-
Insulator	PTFE	-
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω
Frequency		0-18	GHz
VSWR	1.14	+	0.0450 x F(GHz) Maxi
Insertion loss		0.05	√F(GHz) dB Maxi
RF leakage	- (-	- F(GHz) dB Maxi
Voltage rating		500	Veff Maxi
Dielectric withstanding voltage		1000	Veff mini
Insulation resistance		5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		15	N mini
Axial force – Opposite end		15	N mini
Torque		1	N.cm mini
Recommended torque			
Mating		40	N.cm
Panel nut		NA	N.cm
Mating life		100	Cycles mini
Weight		1.8080	g

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

OTHER CHARACTERISTICS

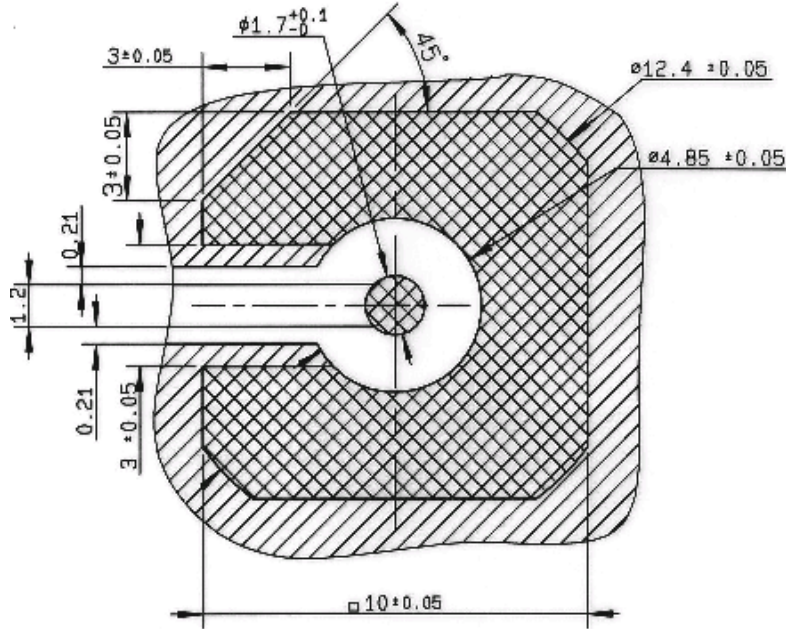
Assembly instruction:

Others:

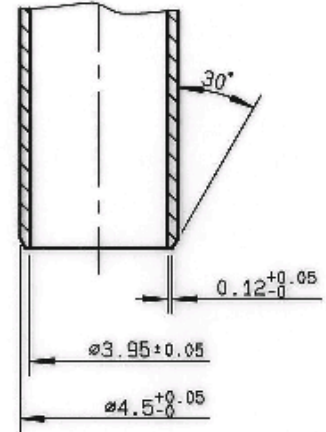
FORCE F1:100N-TORQUES C1:90Ncm-C2:70Ncm

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SMA B SERIES - INFORMATIONS



ASPIRATION PORT



COPLANAR LINE

Pattern and signal are on the same side.

Thickness of PCB : .063 (1.6 mm)

The material of PCB is the epoxy resin
of glass fabrics bacs. ($E_r = 4.8$)

The solder resist should be printed except for the land
pattern on the PCB.

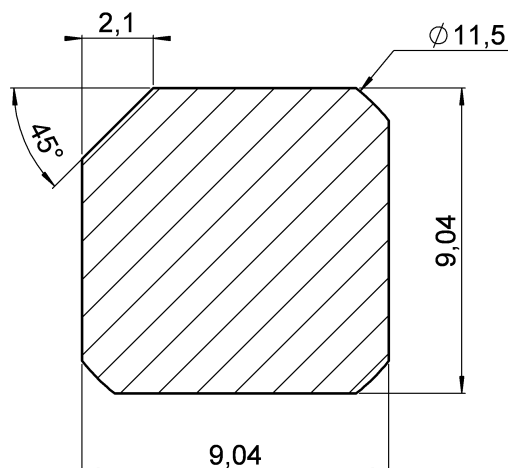


Pattern



Land for solder
paste

SHADOW OF SMA B

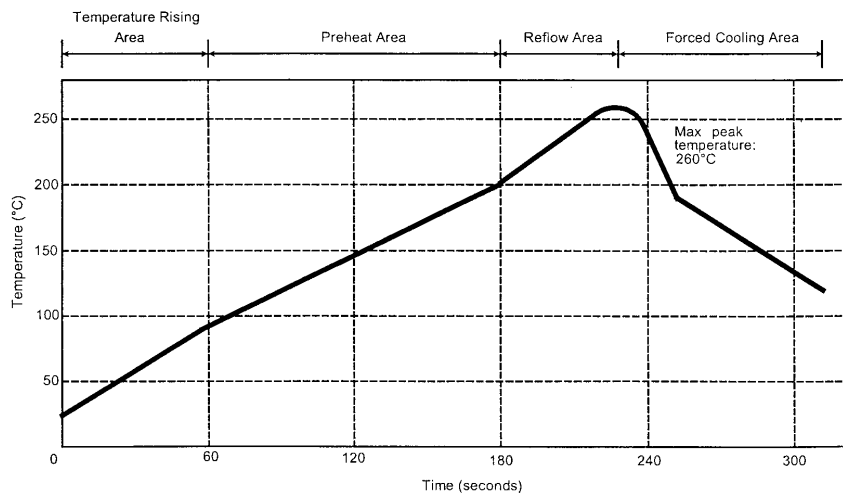


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SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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